

### **Inventor Information**

Inventor One Given Name:: Ikuya  
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City of Residence:: Suwa-shi  
State or Prov. of Residence::  
Country of Residence:: Japan  
Citizenship Country:: Japan

### **Correspondence Information**

Correspondence Customer Number:: 25944

### **Application Information**

Title Line One:: SOLDERING METHOD, SOLDERING DEVICE,  
Title Line Two:: AND METHOD AND DEVICE OF FABRICATING  
Title Line Three:: ELECTRONIC CIRCUIT MODULE  
Total Drawing Sheets:: 5  
Docket Number:: 112155

### **Prior Foreign Applications**

Foreign Application One:: 2001-75534  
Filing Date:: March 16, 2001  
Country:: Japan  
Priority Claimed:: yes

### **Assignee Information**

Name of assignee:: SEIKO EPSON CORPORATION  
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